SLLS032B - DECEMBER 1987 - REVISED MAY 1995

- Meets or Exceeds the Requirements of ANSI Standard EIA/TIA-422-B and ITU Recommendation V.11
- Designed to Operate at 20 Mbaud or Higher
- TTL-and CMOS-Input Compatibility
- Single 5-V Supply Operation
- Output Short-Circuit Protection
- Improved Replacement for the μA9638

# V<sub>CC</sub> 1 8 1Y 1A 2 7 12 2A 3 6 2Y GND 4 5 2Z

# description

The SN75ALS191 is a dual, high-speed, differential line driver designed to meet ANSI Standard EIA/TIA-422-B and ITU Recommendation V.11. The inputs are TTL- and CMOS-compatible and have input clamp diodes. Schottky-diode-clamped transistors minimize propagation delay time. This device operates from a single 5-V power supply and is supplied in eight-pin packages.

The SN75ALS191 is characterized for operation from 0°C to 70°C.

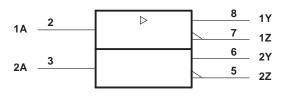
# FUNCTION TABLE (each driver)

INPUTS	OUTPUTS				
Α	Y	Z			
Н	Н	L			
L	L	Н			

H = high level, L = low level,

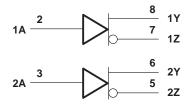
Z = high impedance

# logic symbol†



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# logic diagram (positive logic)



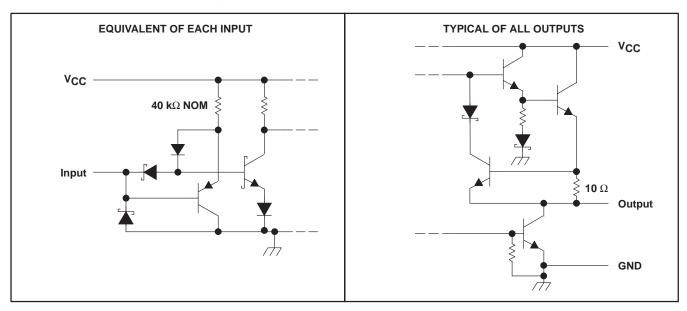


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### schematics of inputs and outputs



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub> (see Note 1)	
Input voltage, V <sub>I</sub>	
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>Stg</sub>	– 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values except differential output voltage (VOD) are with respect to network ground terminal.

### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW
Р	1000 mW	8.0 mW/°C	640 mW

### recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.75	5	5.25	V
High-level input voltage, VIH	2			V
Low-level input voltage, V <sub>IL</sub>			0.8	V
High-level output current, IOH			- 50	mA
Low-level output current, IOL			50	mA
Operating free-air temperature, T <sub>A</sub>	0		70	°C



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# electrical characteristics over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS				TYP <sup>†</sup>	MAX	UNIT
٧ıĸ	Input clamp voltage	V <sub>CC</sub> = 4.75 V,	I <sub>I</sub> = -18 mA			-1	-1.2	V
\/ - · ·	High lovel code of college	$V_{CC} = 4.75 \text{ V},$	V <sub>IH</sub> = 2 V,	I <sub>OH</sub> = - 10 mA	2.5	3.3		V
VOH	High-level output voltage	V <sub>IL</sub> = 0.8 V	L = 0.8 V I <sub>OH</sub> = -40 mA		2			V
VOL	Low-level output voltage	V <sub>CC</sub> = 4.75 V, I <sub>OL</sub> = 40 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V,			0.5	V
VOD1	Differential output voltage	$V_{CC} = 5.25 \text{ V},$	IO = 0				2 V <sub>OD2</sub>	V
VOD2	Differential output voltage				2			V
Δ  V <sub>OD</sub>	Change in magnitude of differential output voltage‡	V <sub>CC</sub> = 4.75 V to	5.25 V,	R <sub>L</sub> = 100 Ω,			± 0.4	V
Voc	Common-mode output voltage§	See Figure 1		_			3	V
∆  Voc	Change in magnitude of common-mode output voltage‡						± 0.4	V
				V <sub>O</sub> = 6 V		0.1	100	
IO	Output current with power off	$V_{CC} = 0$		$V_0 = -0.25 \text{ V}$		-0.1	-100	μΑ
				$V_0 = -0.25 \text{ V to 6 V}$			±100	
II	Input current	$V_{CC} = 5.25 \text{ V},$	V <sub>I</sub> = 5.5 V				50	μΑ
ΙΗ	High-level input current	$V_{CC} = 5.25 \text{ V},$	V <sub>I</sub> = 2.7 V				25	μΑ
I <sub>Ι</sub> Γ	Low-level input current	$V_{CC} = 5.25 \text{ V},$	V <sub>I</sub> = 0.5 V				200	μΑ
los	Short-circuit output current¶	$V_{CC} = 5.25 \text{ V},$	VO = 0		-50		-150	mA
Icc	Supply current (all drivers)	$V_{CC} = 5.25 \text{ V},$	No load,	All inputs at 0 V		32	40	mA

# switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V}$

	PARAMETER	Т	EST CONDITIO	MIN	TYP#	MAX	UNIT	
td(OD)	Differential-output delay time					3.5	7	ns
t <sub>t</sub> (OD)	Differential-output transition time	$C_L = 15 pF$ ,	$R_L = 100 \Omega$ ,	See Figure 2		3.5	7	ns
	Skew	]				1.5	4	ns

<sup>#</sup> Typical values are at  $T_A = 25^{\circ}C$ .



<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V and  $T_A$  = 25°C. ‡  $|V_{OD}|$  and  $|V_{OC}|$  are the changes in magnitude of  $V_{OD}$  and  $V_{OC}$ , respectively, that occur when the input is changed from a high level to a low

<sup>§</sup> In ANSI Standard EIA/TIA-422-B, VOC, which is the average of the two output voltages with respect to ground, is called output offset voltage,

<sup>¶</sup> Only one output at a time should be shorted, and duration of the short circuit should not exceed one second.

### PARAMETER MEASUREMENT INFORMATION

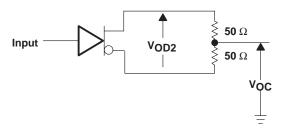
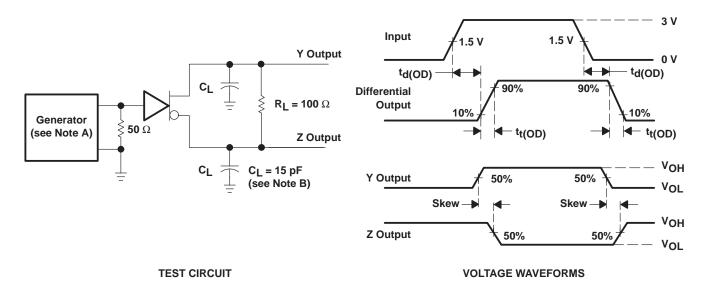


Figure 1. Differential and Common-Mode Output Voltages



NOTES: A. The input pulse generator has the following characteristics:  $Z_O = 50~\Omega$ , PRR  $\leq 500~kHz$ ,  $t_W = 100~ns$ ,  $t_T = \leq 5~ns$ .

B. C<sub>L</sub> includes probe and jig capacitance.

Figure 2. Test Circuit and Voltage Waveforms

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### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75ALS191D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS191DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS191DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS191DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS191DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS191DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS191P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS191PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS191PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS191PSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS191PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# **PACKAGE OPTION ADDENDUM**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS191DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS191PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1





\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS191DR	SOIC	D	8	2500	340.5	338.1	20.6
SN75ALS191PSR	SO	PS	8	2000	346.0	346.0	33.0

# D (R-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### P (R-PDIP-T8)

### PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

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